

~~WHAT IS CLAIMED IS:~~

~~CLAIMS:~~

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1. A method of providing a synthetic resin capping layer on a printed circuit, said printed circuit comprising a printed circuit board which is provided with at least one electric component, and the capping layer exhibiting a variation in mechanical properties in a direction at right angles to said capping layer, characterized in that the capping layer is provided on the printed circuit by injection moulding of a foam-forming reactive injection-moulding material.
2. A method as claimed in Claim 1, characterized in that for the reactive injection-moulding material use is made of a polyurethane-based reactive injection-moulding material.
3. A method as claimed in Claim 1 or 2, characterized in that, to envelop the circuit, the capping layer is provided on both sides of the circuit, thereby forming an encapsulation.
4. A method as claimed in Claim 1, 2 or 3, characterized in that, prior to being provided with the capping layer, the circuit is coated with an elastically compressible buffer layer.
5. A method as claimed in Claim 1, 2 or 3, characterized in that, prior to the provision of the capping layer on the circuit, said circuit is coated with a buffer layer of a deformable viscous material.
6. A method as claimed in Claim 5, characterized in that said deformable viscous material is utilized as a reactant in the reactive injection-moulding process.
7. A method as claimed in ^{Claim 1} any one of Claims 1 to 6, characterized in that the circuit is also provided with a layer which provides a shield against electromagnetic radiation.
8. A printed circuit which is provided with a synthetic resin capping layer, said circuit comprising a printed circuit board having at least one electric component, and the capping layer exhibiting a variation of the mechanical properties in a direction at right angles to the capping layer, characterized in that said variation of the mechanical properties is a continuous variation.
9. A portable apparatus which is provided with a printed circuit obtained by means of the method as claimed in ^{Claim 1} any one of Claims 1 to 7.

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10. A mobile telephone comprising a printed circuit obtained by means of the method as claimed in any one of Claims 1 to 7.
11. A mobile telephone comprising a housing in which a printed circuit is arranged, characterized in that the printed circuit is provided with a synthetic resin capping layer which constitutes the housing of the mobile telephone.

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